



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

**PCN# 20260326003.1
NE555 Timers Design Change
Change Notification / Sample Request**

Date: March 27, 2026

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20260326003.1
Attachment

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
SA555DR	
NA555DR	
SE555P	
SA555DR	
NA555P	
NE555P	
SA555P	
NA555DR	
SE555DR	
NE555DR	
SE555P	
NE555DR	
NE555P	
SE555DR	
NE555PWR	

Technical details of this Product Change follow on the next page(s).

PCN Number:	20260326003.1		PCN Date:	March 27, 2026
Title:	NE555 Timers Design Change			
Customer Contact:	Change Management Team		Dept:	Quality Services
Proposed 1st Ship Date:	June 25, 2026	Sample requests accepted until:	May 26, 2026*	
*Sample requests received after May 26, 2026 will not be supported.				
Change Type:				
☐	Assembly Site	☒	Design	☐
☐	Assembly Process	☒	Data Sheet	☐
☐	Assembly Materials	☐	Part number change	☐
☐	Mechanical Specification	☐	Test Site	☐
☐	Packing/Shipping/Labeling	☐	Test Process	☐
☐			Wafer Bump Material	
☐			Wafer Bump Process	
☐			Wafer Fab Site	
☐			Wafer Fab Material	
☐			Wafer Fab Process	
PCN Details				
Description of Change:				
Texas Instruments is pleased to announce a design change for NE555 Timer Devices. This change addresses customer concerns on previous changes made to the 555 Timers. The datasheets will be changing as a result of the above mentioned changes. The datasheet change details can be reviewed in the datasheet revision history. The links to the revised datasheets are available in the table below.				
 NA555, NE555, SA555, SE555 SLFS022K – SEPTEMBER 1973 – REVISED MARCH 2026				
Changes from Revision J (February 2025) to Revision K (March 2026)				Page
Updated all device characteristic curves in the <i>Typical Characteristics</i> section.....				8
Product Folder	Current Datasheet Number	New Datasheet Number	Link to Full Datasheet	
xx555	SLFS022J	SLFS022K	http://www.ti.com/product/NA555	
Qual details are provided in the Qual Data Section.				
Reason for Change:				
Improve device performance.				
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):				
Review updated datasheets and/or the Standard Data Packet for more details on the changes. Evaluating samples is encouraged				
Impact on Environmental Ratings:				
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.				
RoHS	REACH	Green Status	IEC 62474	
☒ No Change	☒ No Change	☒ No Change	☒ No Change	
Changes to product identification resulting from this PCN:				

Die Rev:
Current

Die Rev [2P]

New

Die Rev [2P]

A, B, D	B
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Sample product shipping label (not actual product label):



Product Affected :

SA555DR	SE555DR	SA555P	SE555P
NA555DR	NE555DR	NA555P	NE555P
NE555PWR			

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: NE555PWR	QBS Package Reference: LM2902BQPWRQ1	QBS Process Reference: MC33063AQDRQ1	QBS Package Reference: LM2901VQPWRQ1	QBS Product Reference: SE555DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	1/77/0	-
UHAST	A3	Unbiased HAST	110C/85%RH	264 Hours	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	3/231/0	-	1/45/0	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-
PD	C4	Physical Dimensions	Cpk>1.67	-	-	3/30/0	-	1/10/0	-
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-	1/3/0
ESD	E2	ESD HBM	-	500 Volts	-	-	-	-	1/3/0

Type	#	Test Name	Condition	Duration	Qual Device: NE555PWR	QBS Package Reference: LM2902BQPWRQ1	QBS Process Reference: MC33063AQDRQ1	QBS Package Reference: LM2901VQPWRQ1	QBS Product Reference: SE555DR
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	1/30/0

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device NE555PWR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-079

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SE555DR	Qual Device: SE555DRG4	Qual Device: NA555DR	Qual Device: SA555DR	Qual Device: NE555DR	QBS Package, Process Reference: MC33063ADR	QBS Package, Process Reference: MC33063AQDRQ1	QBS Package Reference: ULQ2003AQDRQ1	QBS Package Reference: TPS7B4256QDRQ1
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	3/231/0	1/77/0	3/240/0
UHA	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	-	-	1/77/0	-
UHA	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	3/231/0	-	3/240/0
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	3/231/0	3/231/0	1/77/0	3/240/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	3/135/0	1/45/0	3/150/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	1/77/0	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	2/1600/0	3/2400/0	-	-
SD	C3	PB Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	1/30/0

Type	#	Test Name	Condition	Duration	Qual Device: SE555DR	Qual Device: SE555DRG4	Qual Device: NA555DR	Qual Device: SA555DR	Qual Device: NE555DR	QBS Package, Process Reference: MC33063ADR	QBS Package, Process Reference: MC33063AQDRQ1	QBS Package Reference: ULQ2003AQDRQ1	QBS Package Reference: TPS7B4256QDRQ1
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	-	-	-	1/15/0	1/15/0	1/30/0
PD	C4	Physical Dimensions	Cpk>1.67	-	-	-	-	-	-	-	3/30/0	1/10/0	3/30/0
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	500 Volts	1/3/0	-	-	-	-	-	-	-	-
LU	E4	Latch-Up	Per JESD78	-	1/3/0	-	-	-	-	-	-	-	-
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	1/30/0	-	-	-	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device SE555DR is qualified at MSL1 260C
- Qual Device SE555DRG4 is qualified at MSL1 260C
- Qual Device NA555DR is qualified at MSL1 260C
- Qual Device SA555DR is qualified at MSL1 260C
- Qual Device NE555DR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-072

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: SE555P	Qual Device: NA555P	Qual Device: SA555P	Qual Device: NE555P	Qual Device: NE555PE4	QBS Package Reference: NE5532P	QBS Package Reference: UCC37322P	QBS Process Reference: MC33063AQDRQ1	QBS Package Reference: OPA2277P	QBS Package Reference: TL071CP	QBS Package Reference: ULN2003AN	QBS Product Reference: SE555DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	-	-	-	-	3/231/0	-	-	-	-	-	-
UHAST	A3	Autoclave	121C/15psig	96 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	-	-	-	-	-	-	-	1/77/0	1/77/0	1/77/0	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	-	-	-	-	-	3/231/0	-	1/77/0	1/77/0	1/77/0	-
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	-	-	-	-	-	-	-	1/77/0	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	-	-	-	-	-	3/231/0	-	-	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	-	-	-	-	-	3/231/0	-	-	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	-	-	-	-	-	3/2400/0	-	-	-	-
SD	C3	PB-Free Solderability	8 Hours Steam Age	-	-	-	-	-	-	3/66/0	3/66/0	-	-	-	-	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	-	-	-	-	-	-	-	1/3/0
ESD	E2	ESD CDM	-	1500 Volts	1/3/0	-	-	-	-	-	-	-	-	-	-	-
ESD	E2	ESD HBM	-	500 Volts	-	-	-	-	-	-	-	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	-	-	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-	-	-	-	-	-	-	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	1/Pass	-	-	-	-	-	-	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-074

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Name	Condition	Duration	Qual Device: NE555DR	QBS Package Reference: MC33063ADR	QBS Process Reference: MC33063AQDRQ1	QBS Package Reference: LM2901VQPWRQ1	QBS Product Reference: SE555DR
HAST	A2	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-
UHAST	A3	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-	-
TC	A4	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	-	-	-
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-	-
ELFR	B2	Early Life Failure Rate	125C	48 Hours	-	-	3/2400/0	-	-
SD	C3	PB-Free Solderability	Precondition w.155C Dry Bake (4 hrs +/- 15 minutes)	-	-	-	-	1/15/0	-
ESD	E2	ESD CDM	-	1000 Volts	-	-	-	-	1/3/0
ESD	E2	ESD HBM	-	500 Volts	-	-	-	-	1/3/0
LU	E4	Latch-Up	Per JESD78	-	-	-	-	-	1/3/0
CHAR	E5	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	1/30/0
FTY	E6	Final Test Yield	-	-	1/Pass	-	-	-	-

- QBS: Qual By Similarity, also known as Generic Data
- Qual Device NE555DR is qualified at MSL1 260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2509-073

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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